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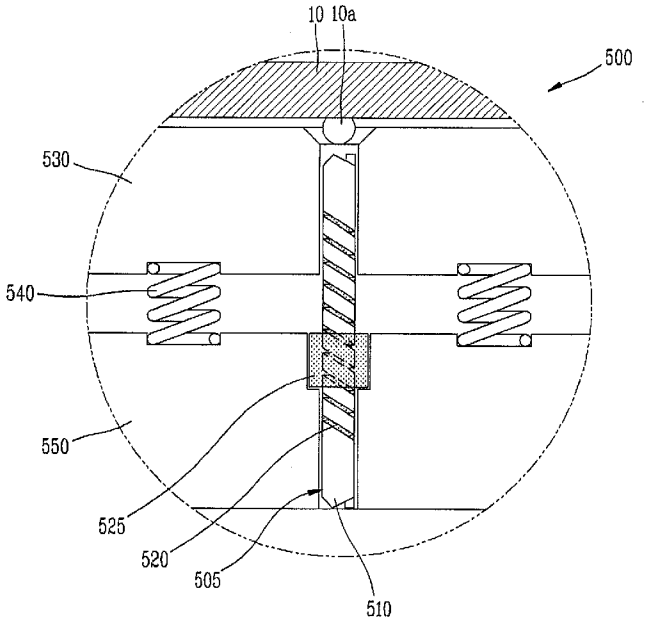
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(54) **Title:** POGO PIN, THE FABRICATION METHOD THEREOF AND TEST SOCKET USING THE SAME



(57) **Abstract:** Disclosed is a pogo pin including: a hollow body having a spring structure by spirally cutting at least a portion of an outer surface thereof; and a conductive material filling at least an inside of the body. According to the present invention, when testing a semiconductor package, error rate in contact between the package, the pogo pin and a test board can be remarkably reduced, and simultaneously can enhance rigidity and electrical conductivity of the pogo pin. Further, simple componentry of the pogo pin can facilitate its fabrication, reduce fabrication costs, and even foresee fabrication of a micro-pogo pin.

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